

SOLDERING APPARATUS, AND AGENT AND METHOD FOR
SOLDER AND SOLDER OXIDES

Abstract of the disclosure:

There are disclosed a soldering apparatus comprising
a solder wave shape forming means for melting solder and
5 forming solder wave shape, and a separating agent dusting
means for dusting solder oxides with a separating agent
which separates solder and solder oxides, wherein said
separating agent is any one selected from the group
consisting of offal, cereal grain or flour, bean flour,
10 seed grain or flour, soybean-cake flour, and peanut hull
flour, or a combination thereof, as well as an agent and a
method for separating solder and solder oxides.

Fig. 1

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